

Welcome to [E-XFL.COM](#)

Understanding **Embedded - FPGAs (Field Programmable Gate Array)**

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

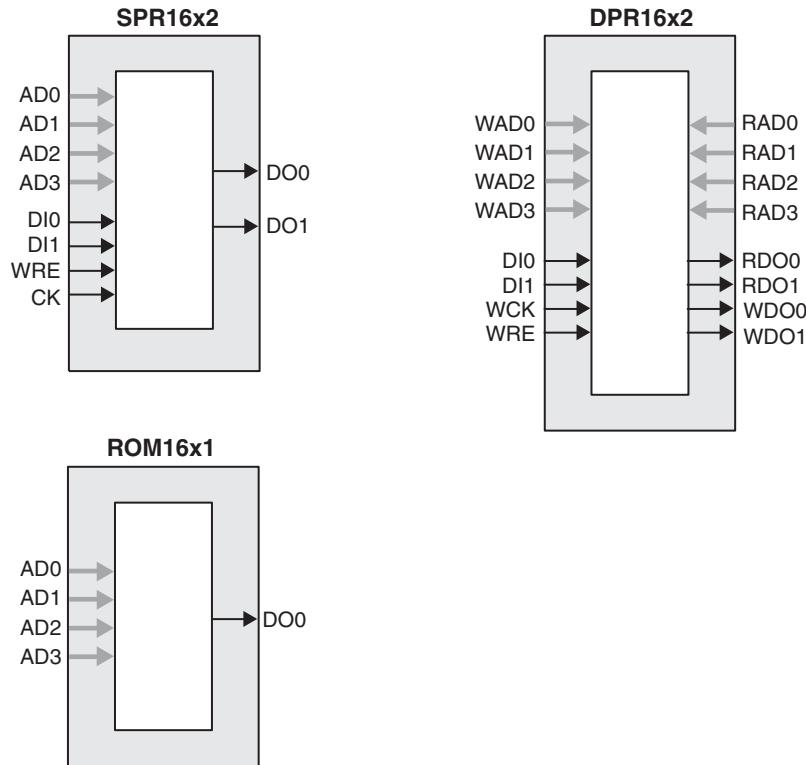
Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details

Product Status	Active
Number of LABs/CLBs	80
Number of Logic Elements/Cells	640
Total RAM Bits	-
Number of I/O	101
Number of Gates	-
Voltage - Supply	1.71V ~ 3.465V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	132-LFBGA, CSPBGA
Supplier Device Package	132-CSPBGA (8x8)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lcmxo640c-5mn132c

Figure 2-6. Distributed Memory Primitives



ROM Mode: The ROM mode uses the same principal as the RAM modes, but without the Write port. Pre-loading is accomplished through the programming interface during configuration.

PFU Modes of Operation

Slices can be combined within a PFU to form larger functions. Table 2-4 tabulates these modes and documents the functionality possible at the PFU level.

Table 2-4. PFU Modes of Operation

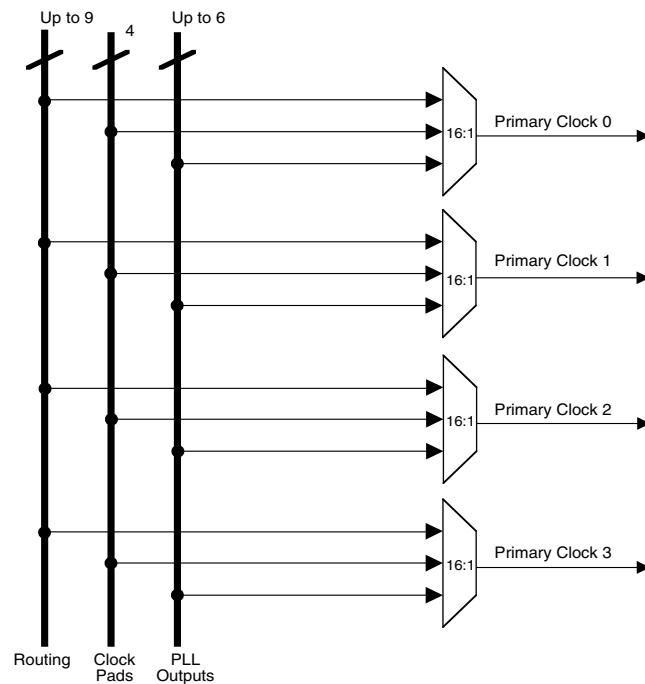
Logic	Ripple	RAM	ROM
LUT 4x8 or MUX 2x1 x 8	2-bit Add x 4	SPR16x2 x 4 DPR16x2 x 2	ROM16x1 x 8
LUT 5x4 or MUX 4x1 x 4	2-bit Sub x 4	SPR16x4 x 2 DPR16x4 x 1	ROM16x2 x 4
LUT 6x2 or MUX 8x1 x 2	2-bit Counter x 4	SPR16x8 x 1	ROM16x4 x 2
LUT 7x1 or MUX 16x1 x 1	2-bit Comp x 4		ROM16x8 x 1

Routing

There are many resources provided in the MachXO devices to route signals individually or as buses with related control signals. The routing resources consist of switching circuitry, buffers and metal interconnect (routing) segments.

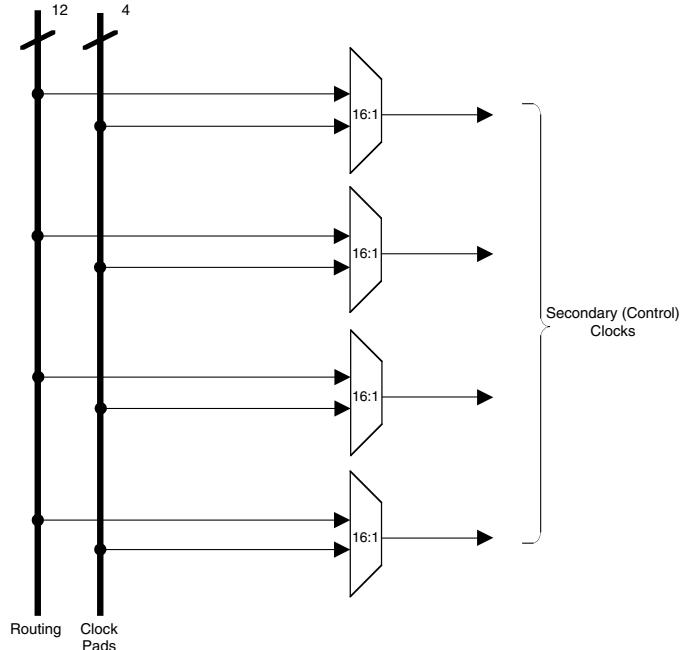
The inter-PFU connections are made with three different types of routing resources: x1 (spans two PFUs), x2 (spans three PFUs) and x6 (spans seven PFUs). The x1, x2, and x6 connections provide fast and efficient connections in the horizontal and vertical directions.

Figure 2-8. Primary Clocks for MachXO1200 and MachXO2280 Devices



Four secondary clocks are generated from four 16:1 muxes as shown in Figure 2-9. Four of the secondary clock sources come from dual function clock pins and 12 come from internal routing.

Figure 2-9. Secondary Clocks for MachXO Devices



sysCLOCK Phase Locked Loops (PLLs)

The MachXO1200 and MachXO2280 provide PLL support. The source of the PLL input divider can come from an external pin or from internal routing. There are four sources of feedback signals to the feedback divider: from CLKINTFB (internal feedback port), from the global clock nets, from the output of the post scalar divider, and from the routing (or from an external pin). There is a PLL_LOCK signal to indicate that the PLL has locked on to the input clock signal. Figure 2-10 shows the sysCLOCK PLL diagram.

The setup and hold times of the device can be improved by programming a delay in the feedback or input path of the PLL which will advance or delay the output clock with reference to the input clock. This delay can be either programmed during configuration or can be adjusted dynamically. In dynamic mode, the PLL may lose lock after adjustment and not relock until the t_{LOCK} parameter has been satisfied. Additionally, the phase and duty cycle block allows the user to adjust the phase and duty cycle of the CLKOS output.

The sysCLOCK PLLs provide the ability to synthesize clock frequencies. Each PLL has four dividers associated with it: input clock divider, feedback divider, post scalar divider, and secondary clock divider. The input clock divider is used to divide the input clock signal, while the feedback divider is used to multiply the input clock signal. The post scalar divider allows the VCO to operate at higher frequencies than the clock output, thereby increasing the frequency range. The secondary divider is used to derive lower frequency outputs.

Figure 2-10. PLL Diagram

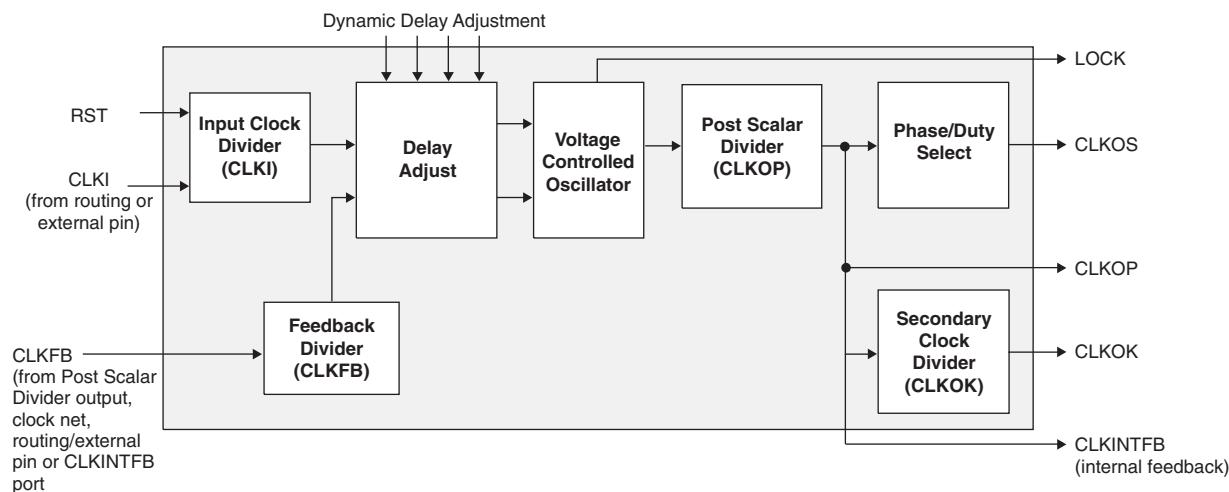


Figure 2-11 shows the available macros for the PLL. Table 2-5 provides signal description of the PLL Block.

Figure 2-11. PLL Primitive

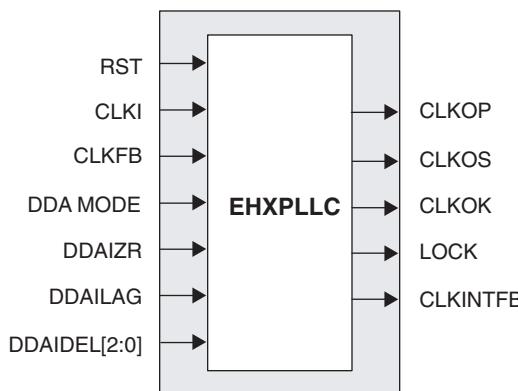


Table 2-8. I/O Support Device by Device

	MachXO256	MachXO640	MachXO1200	MachXO2280
Number of I/O Banks	2	4	8	8
Type of Input Buffers	Single-ended (all I/O Banks)	Single-ended (all I/O Banks)	Single-ended (all I/O Banks) Differential Receivers (all I/O Banks)	Single-ended (all I/O Banks) Differential Receivers (all I/O Banks)
Types of Output Buffers	Single-ended buffers with complementary outputs (all I/O Banks)	Single-ended buffers with complementary outputs (all I/O Banks)	Single-ended buffers with complementary outputs (all I/O Banks) Differential buffers with true LVDS outputs (50% on left and right side)	Single-ended buffers with complementary outputs (all I/O Banks) Differential buffers with true LVDS outputs (50% on left and right side)
Differential Output Emulation Capability	All I/O Banks	All I/O Banks	All I/O Banks	All I/O Banks
PCI Support	No	No	Top side only	Top side only

Table 2-9. Supported Input Standards

Input Standard	VCCIO (Typ.)				
	3.3V	2.5V	1.8V	1.5V	1.2V
Single Ended Interfaces					
LVTTL	Yes	Yes	Yes	Yes	Yes
LVCMOS33	Yes	Yes	Yes	Yes	Yes
LVCMOS25	Yes	Yes	Yes	Yes	Yes
LVCMOS18			Yes		
LVCMOS15				Yes	
LVCMOS12	Yes	Yes	Yes	Yes	Yes
PCI ¹	Yes				
Differential Interfaces					
BLVDS ² , LVDS ² , LVPECL ² , RSDS ²	Yes	Yes	Yes	Yes	Yes

1. Top Banks of MachXO1200 and MachXO2280 devices only.

2. MachXO1200 and MachXO2280 devices only.

Device Configuration

All MachXO devices contain a test access port that can be used for device configuration and programming.

The non-volatile memory in the MachXO can be configured in two different modes:

- In IEEE 1532 mode via the IEEE 1149.1 port. In this mode, the device is off-line and I/Os are controlled by BSCAN registers.
- In background mode via the IEEE 1149.1 port. This allows the device to remain operational in user mode while reprogramming takes place.

The SRAM configuration memory can be configured in three different ways:

- At power-up via the on-chip non-volatile memory.
- After a refresh command is issued via the IEEE 1149.1 port.
- In IEEE 1532 mode via the IEEE 1149.1 port.

Figure 2-22 provides a pictorial representation of the different programming modes available in the MachXO devices. On power-up, the SRAM is ready to be configured with IEEE 1149.1 serial TAP port using IEEE 1532 protocols.

Leave Alone I/O

When using IEEE 1532 mode for non-volatile memory programming, SRAM configuration, or issuing a refresh command, users may specify I/Os as high, low, tristated or held at current value. This provides excellent flexibility for implementing systems where reconfiguration or reprogramming occurs on-the-fly.

TransFR (Transparent Field Reconfiguration)

TransFR (TFR) is a unique Lattice technology that allows users to update their logic in the field without interrupting system operation using a single ispVM command. See TN1087, [Minimizing System Interruption During Configuration Using TransFR Technology](#) for details.

Security

The MachXO devices contain security bits that, when set, prevent the readback of the SRAM configuration and non-volatile memory spaces. Once set, the only way to clear the security bits is to erase the memory space.

For more information on device configuration, please see details of additional technical documentation at the end of this data sheet.

Supply Current (Sleep Mode)^{1,2}

Symbol	Parameter	Device	Typ. ³	Max.	Units
I_{CC}	Core Power Supply	LCMxo256C	12	25	μA
		LCMxo640C	12	25	μA
		LCMxo1200C	12	25	μA
		LCMxo2280C	12	25	μA
I_{CCAUX}	Auxiliary Power Supply	LCMxo256C	1	15	μA
		LCMxo640C	1	25	μA
		LCMxo1200C	1	45	μA
		LCMxo2280C	1	85	μA
I_{CCIO}	Bank Power Supply ⁴	All LCMxo 'C' Devices	2	30	μA

1. Assumes all inputs are configured as LVCMOS and held at the VCCIO or GND.

2. Frequency = 0MHz.

3. $T_A = 25^\circ C$, power supplies at nominal voltage.

4. Per Bank.

Supply Current (Standby)^{1, 2, 3, 4}

Over Recommended Operating Conditions

Symbol	Parameter	Device	Typ. ⁵	Units
I_{CC}	Core Power Supply	LCMxo256C	7	mA
		LCMxo640C	9	mA
		LCMxo1200C	14	mA
		LCMxo2280C	20	mA
		LCMxo256E	4	mA
		LCMxo640E	6	mA
		LCMxo1200E	10	mA
		LCMxo2280E	12	mA
I_{CCAUX}	Auxiliary Power Supply $V_{CCAUX} = 3.3V$	LCMxo256E/C	5	mA
		LCMxo640E/C	7	mA
		LCMxo1200E/C	12	mA
		LCMxo2280E/C	13	mA
I_{CCIO}	Bank Power Supply ⁶	All devices	2	mA

1. For further information on supply current, please see details of additional technical documentation at the end of this data sheet.

2. Assumes all outputs are tristated, all inputs are configured as LVCMOS and held at V_{CCIO} or GND.

3. Frequency = 0MHz.

4. User pattern = blank.

5. $T_J = 25^\circ C$, power supplies at nominal voltage.

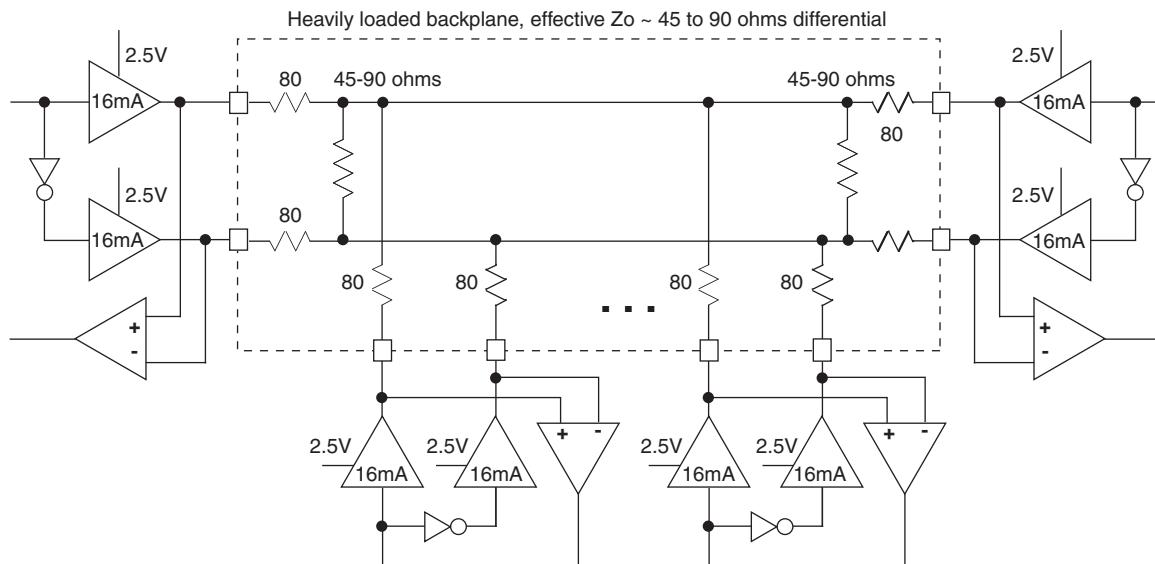
6. Per Bank. $V_{CCIO} = 2.5V$. Does not include pull-up/pull-down.

Table 3-1. LVDS DC Conditions
Over Recommended Operating Conditions

Parameter	Description	Typical	Units
Z_{OUT}	Output impedance	20	Ω
R_S	Driver series resistor	294	Ω
R_P	Driver parallel resistor	121	Ω
R_T	Receiver termination	100	Ω
V_{OH}	Output high voltage	1.43	V
V_{OL}	Output low voltage	1.07	V
V_{OD}	Output differential voltage	0.35	V
V_{CM}	Output common mode voltage	1.25	V
Z_{BACK}	Back impedance	100	Ω
I_{DC}	DC output current	3.66	mA

BLVDS

The MachXO family supports the BLVDS standard through emulation. The output is emulated using complementary LVCMS outputs in conjunction with a parallel external resistor across the driver outputs. The input standard is supported by the LVDS differential input buffer on certain devices. BLVDS is intended for use when multi-drop and bi-directional multi-point differential signaling is required. The scheme shown in Figure 3-2 is one possible solution for bi-directional multi-point differential signals.

Figure 3-2. BLVDS Multi-point Output Example


MachXO Internal Timing Parameters¹

Over Recommended Operating Conditions

Parameter	Description	-5		-4		-3		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
PFU/PFF Logic Mode Timing								
t _{LUT4_PFU}	LUT4 delay (A to D inputs to F output)	—	0.28	—	0.34	—	0.39	ns
t _{LUT6_PFU}	LUT6 delay (A to D inputs to OFX output)	—	0.44	—	0.53	—	0.62	ns
t _{LSR_PFU}	Set/Reset to output of PFU	—	0.90	—	1.08	—	1.26	ns
t _{SUM_PFU}	Clock to Mux (M0,M1) input setup time	0.10	—	0.13	—	0.15	—	ns
t _{HM_PFU}	Clock to Mux (M0,M1) input hold time	-0.05	—	-0.06	—	-0.07	—	ns
t _{SUD_PFU}	Clock to D input setup time	0.13	—	0.16	—	0.18	—	ns
t _{HD_PFU}	Clock to D input hold time	-0.03	—	-0.03	—	-0.04	—	ns
t _{CK2Q_PFU}	Clock to Q delay, D-type register configuration	—	0.40	—	0.48	—	0.56	ns
t _{LE2Q_PFU}	Clock to Q delay latch configuration	—	0.53	—	0.64	—	0.74	ns
t _{LD2Q_PFU}	D to Q throughput delay when latch is enabled	—	0.55	—	0.66	—	0.77	ns
PFU Dual Port Memory Mode Timing								
t _{CORAM_PFU}	Clock to Output	—	0.40	—	0.48	—	0.56	ns
t _{SUDATA_PFU}	Data Setup Time	-0.18	—	-0.22	—	-0.25	—	ns
t _{HDATA_PFU}	Data Hold Time	0.28	—	0.34	—	0.39	—	ns
t _{SUADDR_PFU}	Address Setup Time	-0.46	—	-0.56	—	-0.65	—	ns
t _{HADDR_PFU}	Address Hold Time	0.71	—	0.85	—	0.99	—	ns
t _{SUWREN_PFU}	Write/Read Enable Setup Time	-0.22	—	-0.26	—	-0.30	—	ns
t _{HWREN_PFU}	Write/Read Enable Hold Time	0.33	—	0.40	—	0.47	—	ns
PIO Input/Output Buffer Timing								
t _{IN_PIO}	Input Buffer Delay	—	0.75	—	0.90	—	1.06	ns
t _{OUT_PIO}	Output Buffer Delay	—	1.29	—	1.54	—	1.80	ns
EBR Timing (1200 and 2280 Devices Only)								
t _{CO_EBR}	Clock to output from Address or Data with no output register	—	2.24	—	2.69	—	3.14	ns
t _{COO_EBR}	Clock to output from EBR output Register	—	0.54	—	0.64	—	0.75	ns
t _{SUDATA_EBR}	Setup Data to EBR Memory	-0.26	—	-0.31	—	-0.37	—	ns
t _{HDATA_EBR}	Hold Data to EBR Memory	0.41	—	0.49	—	0.57	—	ns
t _{SUADDR_EBR}	Setup Address to EBR Memory	-0.26	—	-0.31	—	-0.37	—	ns
t _{HADDR_EBR}	Hold Address to EBR Memory	0.41	—	0.49	—	0.57	—	ns
t _{SUWREN_EBR}	Setup Write/Read Enable to EBR Memory	-0.17	—	-0.20	—	-0.23	—	ns
t _{HWREN_EBR}	Hold Write/Read Enable to EBR Memory	0.26	—	0.31	—	0.36	—	ns
t _{SUCE_EBR}	Clock Enable Setup Time to EBR Output Register	0.19	—	0.23	—	0.27	—	ns
t _{HCE_EBR}	Clock Enable Hold Time to EBR Output Register	-0.13	—	-0.16	—	-0.18	—	ns
t _{RSTO_EBR}	Reset To Output Delay Time from EBR Output Register	—	1.03	—	1.23	—	1.44	ns
PLL Parameters (1200 and 2280 Devices Only)								
t _{RSTREC}	Reset Recovery to Rising Clock	1.00	—	1.00	—	1.00	—	ns
t _{RSTSU}	Reset Signal Setup Time	1.00	—	1.00	—	1.00	—	ns

1. Internal parameters are characterized but not tested on every device.

Rev. A 0.19

LCMxo256 and LCMxo640 Logic Signal Connections: 100 csBGA

LCMxo256					LCMxo640				
Ball Number	Ball Function	Bank	Dual Function	Differential	Ball Number	Ball Function	Bank	Dual Function	Differential
B1	PL2A	1		T	B1	PL2A	3		T
C1	PL2B	1		C	C1	PL2C	3		T
D2	PL3A	1		T	D2	PL2B	3		C
D1	PL3B	1		C	D1	PL2D	3		C
C2	PL3C	1		T	C2	PL3A	3		T
E1	PL3D	1		C	E1	PL3B	3		C
E2	PL4A	1		T	E2	PL3C	3		T
F1	PL4B	1		C	F1	PL3D	3		C
F2	PL5A	1		T	F2	PL4A	3		
G2	PL5B	1		C	G2	PL4C	3		T
H1	GNDIO1	1			H1	GNDIO3	3		
H2	PL5C	1		T	H2	PL4D	3		C
J1	PL5D	1	GSRN	C	J1	PL5B	3	GSRN	
J2	PL6A	1		T	J2	PL7B	3		
K1	PL6B	1	TSALL	C	K1	PL8C	3	TSALL	T
K2	PL7A	1		T	K2	PL8D	3		C
L1	PL7B	1		C	L1	PL9A	3		
L2	PL7C	1		T	L2	PL9C	3		
M1	PL7D	1		C	M1	PL10A	3		
M2	PL8A	1		T	M2	PL10C	3		
N1	PL8B	1		C	N1	PL11A	3		
M3	PL9A	1		T	M3	PL11C	3		
N2	GNDIO1	1			N2	GNDIO3	3		
P2	TMS	1	TMS		P2	TMS	2	TMS	
P3	PL9B	1		C	P3	PB2C	2		
N4	TCK	1	TCK		N4	TCK	2	TCK	
P4	PB2A	1		T	P4	VCCIO2	2		
N3	PB2B	1		C	N3	GNDIO2	2		
P5	TDO	1	TDO		P5	TDO	2	TDO	
N5	PB2C	1		T	N5	PB4C	2		
P6	TDI	1	TDI		P6	TDI	2	TDI	
N6	PB2D	1		C	N6	PB4E	2		
P7	VCC	-			P7	VCC	-		
N7	PB3A	1	PCLK1_1**	T	N7	PB5B	2	PCLK2_1**	
P8	PB3B	1		C	P8	PB5D	2		
N8	PB3C	1	PCLK1_0**	T	N8	PB6B	2	PCLK2_0**	
P9	PB3D	1		C	P9	PB6C	2		
N10	GNDIO1	1			N10	GNDIO2	2		
P11	PB4A	1		T	P11	PB8B	2		
N11	PB4B	1		C	N11	PB8C	2		T
P12	PB4C	1		T	P12	PB8D	2		C
N12	PB4D	1		C	N12	PB9A	2		

LCMxo256 and LCMxo640 Logic Signal Connections: 100 csBGA (Cont.)

LCMxo256					LCMxo640				
Ball Number	Ball Function	Bank	Dual Function	Differential	Ball Number	Ball Function	Bank	Dual Function	Differential
P13	PB5A	1			P13	PB9C	2		T
M12*	SLEEPN	-	SLEEPN		M12*	SLEEPN	-	SLEEPN	
P14	PB5C	1		T	P14	PB9D	2		C
N13	PB5D	1		C	N13	PB9F	2		
N14	PR9B	0		C	N14	PR11D	1		C
M14	PR9A	0		T	M14	PR11B	1		C
L13	PR8B	0		C	L13	PR11C	1		T
L14	PR8A	0		T	L14	PR11A	1		T
M13	PR7D	0		C	M13	PR10D	1		C
K14	PR7C	0		T	K14	PR10C	1		T
K13	PR7B	0		C	K13	PR10B	1		C
J14	PR7A	0		T	J14	PR10A	1		T
J13	PR6B	0		C	J13	PR9D	1		
H13	PR6A	0		T	H13	PR9B	1		
G14	GNDIO0	0			G14	GNDIO1	1		
G13	PR5D	0		C	G13	PR7B	1		
F14	PR5C	0		T	F14	PR6C	1		
F13	PR5B	0		C	F13	PR6B	1		
E14	PR5A	0		T	E14	PR5D	1		
E13	PR4B	0		C	E13	PR5B	1		
D14	PR4A	0		T	D14	PR4D	1		
D13	PR3D	0		C	D13	PR4B	1		
C14	PR3C	0		T	C14	PR3D	1		
C13	PR3B	0		C	C13	PR3B	1		
B14	PR3A	0		T	B14	PR2D	1		
C12	PR2B	0		C	C12	PR2B	1		
B13	GNDIO0	0			B13	GNDIO1	1		
A13	PR2A	0		T	A13	PT9F	0		C
A12	PT5C	0			A12	PT9E	0		T
B11	PT5B	0		C	B11	PT9C	0		
A11	PT5A	0		T	A11	PT9A	0		
B12	PT4F	0		C	B12	VCCIO0	0		
A10	PT4E	0		T	A10	GNDIO0	0		
B10	PT4D	0		C	B10	PT7E	0		
A9	PT4C	0		T	A9	PT7A	0		
A8	PT4B	0	PCLK0_1**	C	A8	PT6B	0	PCLK0_1**	
B8	PT4A	0	PCLK0_0**	T	B8	PT5B	0	PCLK0_0**	C
A7	PT3D	0		C	A7	PT5A	0		T
B7	VCCAUX	-			B7	VCCAUX	-		
A6	PT3C	0		T	A6	PT4F	0		
B6	VCC	-			B6	VCC	-		
A5	PT3B	0		C	A5	PT3F	0		

**LCMxo640, LCMxo1200 and LCMxo2280 Logic Signal Connections:
 256 caBGA / 256 ftBGA (Cont.)**

LCMxo640				LCMxo1200				LCMxo2280					
Ball Number	Ball Function	Bank	Dual Function	Ball Number	Ball Function	Bank	Dual Function	Ball Number	Ball Function	Bank	Dual Function		
J4	PL8A	3	T	J4	PL13A	6	T*	J4	PL16A	6	T*		
J5	PL8B	3	C	J5	PL13B	6	C*	J5	PL16B	6	C*		
R1	PL11A	3	T	R1	PL13C	6	T	R1	PL16C	6	T		
R2	PL11B	3	C	R2	PL13D	6	C	R2	PL16D	6	C		
-	-	-	-	-	-	-	-	GND	GND	-	-		
K5	NC			K5	PL14A	6	LLM0_PLLT_FB_A	T*	K5	PL17A	6	LLM0_PLLT_FB_A	
K4	NC			K4	PL14B	6	LLM0_PLLC_FB_A	C*	K4	PL17B	6	LLM0_PLLC_FB_A	
L5	PL10C	3	T	L5	PL14C	6	T	L5	PL17C	6	T		
L4	PL10D	3	C	L4	PL14D	6	C	L4	PL17D	6	C		
M5	NC			M5	PL15A	6	LLM0_PLLT_IN_A	T*	M5	PL18A	6	LLM0_PLLT_IN_A	
M4	NC			M4	PL15B	6	LLM0_PLLC_IN_A	C*	M4	PL18B	6	LLM0_PLLC_IN_A	
N4	PL11C	3	T	N4	PL16A	6	T	N4	PL19A	6	T		
N3	PL11D	3	C	N3	PL16B	6	C	N3	PL19B	6	C		
VCCIO3	VCCIO3	3		VCCIO6	VCCIO6	6		VCCIO6	VCCIO6	6			
GND	GNDIO3	3		GND	GNDIO6	6		GND	GNDIO6	6			
GND	GNDIO2	2		GND	GNDIO5	5		GND	GNDIO5	5			
VCCIO2	VCCIO2	2		VCCIO5	VCCIO5	5		VCCIO5	VCCIO5	5			
P4	TMS	2	TMS	P4	TMS	5	TMS	P4	TMS	5	TMS		
P2	NC			P2	PB2A	5	T	P2	PB2A	5	T		
P3	NC			P3	PB2B	5	C	P3	PB2B	5	C		
N5	NC			N5	PB2C	5	T	N5	PB2C	5	T		
R3	TCK	2	TCK	R3	TCK	5	TCK	R3	TCK	5	TCK		
N6	NC			N6	PB2D	5	C	N6	PB2D	5	C		
T2	PB2A	2	T	T2	PB3A	5	T	T2	PB3A	5	T		
T3	PB2B	2	C	T3	PB3B	5	C	T3	PB3B	5	C		
R4	PB2C	2	T	R4	PB3C	5	T	R4	PB3C	5	T		
R5	PB2D	2	C	R5	PB3D	5	C	R5	PB3D	5	C		
P5	PB3A	2	T	P5	PB4A	5	T	P5	PB4A	5	T		
P6	PB3B	2	C	P6	PB4B	5	C	P6	PB4B	5	C		
T5	PB3C	2	T	T5	PB4C	5	T	T5	PB4C	5	T		
M6	TDO	2	TDO	M6	TDO	5	TDO	M6	TDO	5	TDO		
T4	PB3D	2	C	T4	PB4D	5	C	T4	PB4D	5	C		
R6	PB4A	2	T	R6	PB5A	5	T	R6	PB5A	5	T		
GND	GNDIO2	2		GND	GNDIO5	5		GND	GNDIO5	5			
VCCIO2	VCCIO2	2		VCCIO5	VCCIO5	5		VCCIO5	VCCIO5	5			
T6	PB4B	2	C	T6	PB5B	5	C	T6	PB5B	5	C		
N7	TDI	2	TDI	N7	TDI	5	TDI	N7	TDI	5	TDI		
T8	PB4C	2	T	T8	PB5C	5	T	T8	PB6A	5	T		
T7	PB4D	2	C	T7	PB5D	5	C	T7	PB6B	5	C		
M7	NC			M7	PB6A	5	T	M7	PB7C	5	T		
M8	NC			M8	PB6B	5	C	M8	PB7D	5	C		
T9	VCCAUX	-		T9	VCCAUX	-		T9	VCCAUX	-			
R7	PB4E	2	T	R7	PB6C	5	T	R7	PB8C	5	T		
R8	PB4F	2	C	R8	PB6D	5	C	R8	PB8D	5	C		
-	-			VCCIO5	VCCIO5	5		VCCIO5	VCCIO5	5			
-	-			GND	GNDIO5	5		GND	GNDIO5	5			
P7	PB5C	2	T	P7	PB6E	5	T	P7	PB9A	4	T		
P8	PB5D	2	C	P8	PB6F	5	C	P8	PB9B	4	C		
N8	PB5A	2	T	N8	PB7A	4	T	N8	PB10E	4	T		
N9	PB5B	2	PCLK2_1***	C	N9	PB7B	4	PCLK4_1***	C	N9	PB10F	4	PCLK4_1***
P10	PB7B	2	C	P10	PB7D	4	C	P10	PB10D	4	C		
P9	PB7A	2	T	P9	PB7C	4	T	P9	PB10C	4	T		
M9	PB6B	2	PCLK2_0***	C	M9	PB7F	4	PCLK4_0***	C	M9	PB10B	4	PCLK4_0***

LCMxo2280 Logic Signal Connections: 324 ftBGA (Cont.)

LCMxo2280				
Ball Number	Ball Function	Bank	Dual Function	Differential
V10	PB9B	4		C
N10	PB9C	4		T
R10	PB9D	4		C
P10	PB10F	4	PCLK4_1***	C
T10	PB10E	4		T
U10	PB10D	4		C
V11	PB10C	4		T
U11	PB10B	4	PCLK4_0***	C
VCCIO4	VCCIO4	4		
GND	GNDIO4	4		
T11	PB10A	4		T
U12	PB11A	4		T
R11	PB11B	4		C
GND	GND	-		
T12	PB11C	4		T
P11	PB11D	4		C
V12	PB12A	4		T
V13	PB12B	4		C
R12	PB12C	4		T
N11	PB12D	4		C
U13	PB12E	4		T
VCCIO4	VCCIO4	4		
GND	GNDIO4	4		
V14	PB12F	4		C
T13	PB13A	4		T
P12	PB13B	4		C
R13	PB13C	4		T
N12	PB13D	4		C
V15	PB14A	4		T
U14	PB14B	4		C
V16	PB14C	4		T
GND	GND	-		
T14	PB14D	4		C
U15	PB15A	4		T
V17	PB15B	4		C
P13**	SLEEPN	-	SLEEPN	
T15	PB15D	4		
U16	PB16A	4		T
V18	PB16B	4		C
N13	PB16C	4		T
R14	PB16D	4		C
VCCIO4	VCCIO4	4		
GND	GNDIO4	4		

LCMxo2280 Logic Signal Connections: 324 ftBGA (Cont.)

LCMxo2280				
Ball Number	Ball Function	Bank	Dual Function	Differential
GND	GNDIO3	3		
VCCIO3	VCCIO3	3		
P15	PR20B	3		C
N14	PR20A	3		T
N15	PR19B	3		C
M13	PR19A	3		T
R15	PR18B	3		C*
T16	PR18A	3		T*
N16	PR17D	3		C
M14	PR17C	3		T
U17	PR17B	3		C*
VCC	VCC	-		
U18	PR17A	3		T*
R17	PR16D	3		C
R16	PR16C	3		T
P16	PR16B	3		C*
VCCIO3	VCCIO3	3		
GND	GNDIO3	3		
P17	PR16A	3		T*
L13	PR15D	3		C
M15	PR15C	3		T
T17	PR15B	3		C*
T18	PR15A	3		T*
L14	PR14D	3		C
L15	PR14C	3		T
R18	PR14B	3		C*
P18	PR14A	3		T*
GND	GND	-		
K15	PR13D	3		C
K13	PR13C	3		T
N17	PR13B	3		C*
N18	PR13A	3		T*
K16	PR12D	3		C
K14	PR12C	3		T
M16	PR12B	3		C*
L16	PR12A	3		T*
GND	GNDIO3	3		
VCCIO3	VCCIO3	3		
J16	PR11D	3		C
J14	PR11C	3		T
M17	PR11B	3		C*
L17	PR11A	3		T*
J15	PR10D	2		C

LCMXO2280 Logic Signal Connections: 324 ftBGA (Cont.)

LCMXO2280				
Ball Number	Ball Function	Bank	Dual Function	Differential
A10	PT8E	0		T
VCCIO0	VCCIO0	0		
GND	GNDIO0	0		
A9	PT8D	0		C
C9	PT8C	0		T
B9	PT8B	0		C
F9	VCCAUX	-		
A8	PT8A	0		T
B8	PT7D	0		C
C8	PT7C	0		T
VCC	VCC	-		
A7	PT7B	0		C
B7	PT7A	0		T
A6	PT6A	0		T
B6	PT6B	0		C
D8	PT6C	0		T
F8	PT6D	0		C
C7	PT6E	0		T
E8	PT6F	0		C
D7	PT5D	0		C
VCCIO0	VCCIO0	0		
GND	GNDIO0	0		
E7	PT5C	0		T
A5	PT5B	0		C
C6	PT5A	0		T
B5	PT4A	0		T
A4	PT4B	0		C
D6	PT4C	0		T
F7	PT4D	0		C
B4	PT4E	0		T
GND	GND	-		
C5	PT4F	0		C
F6	PT3D	0		C
E5	PT3C	0		T
E6	PT3B	0		C
D5	PT3A	0		T
A3	PT2D	0		C
C4	PT2C	0		T
A2	PT2B	0		C
B2	PT2A	0		T
VCCIO0	VCCIO0	0		
GND	GNDIO0	0		
E14	GND	-		

Thermal Management

Thermal management is recommended as part of any sound FPGA design methodology. To assess the thermal characteristics of a system, Lattice specifies a maximum allowable junction temperature in all device data sheets. Designers must complete a thermal analysis of their specific design to ensure that the device and package do not exceed the junction temperature limits. Refer to the [Thermal Management](#) document to find the device/package specific thermal values.

For Further Information

For further information regarding Thermal Management, refer to the following:

- [Thermal Management](#) document
- TN1090 - [Power Estimation and Management for MachXO Devices](#)
- Power Calculator tool included with the Lattice ispLEVER design tool, or as a standalone download from www.latticesemi.com/software

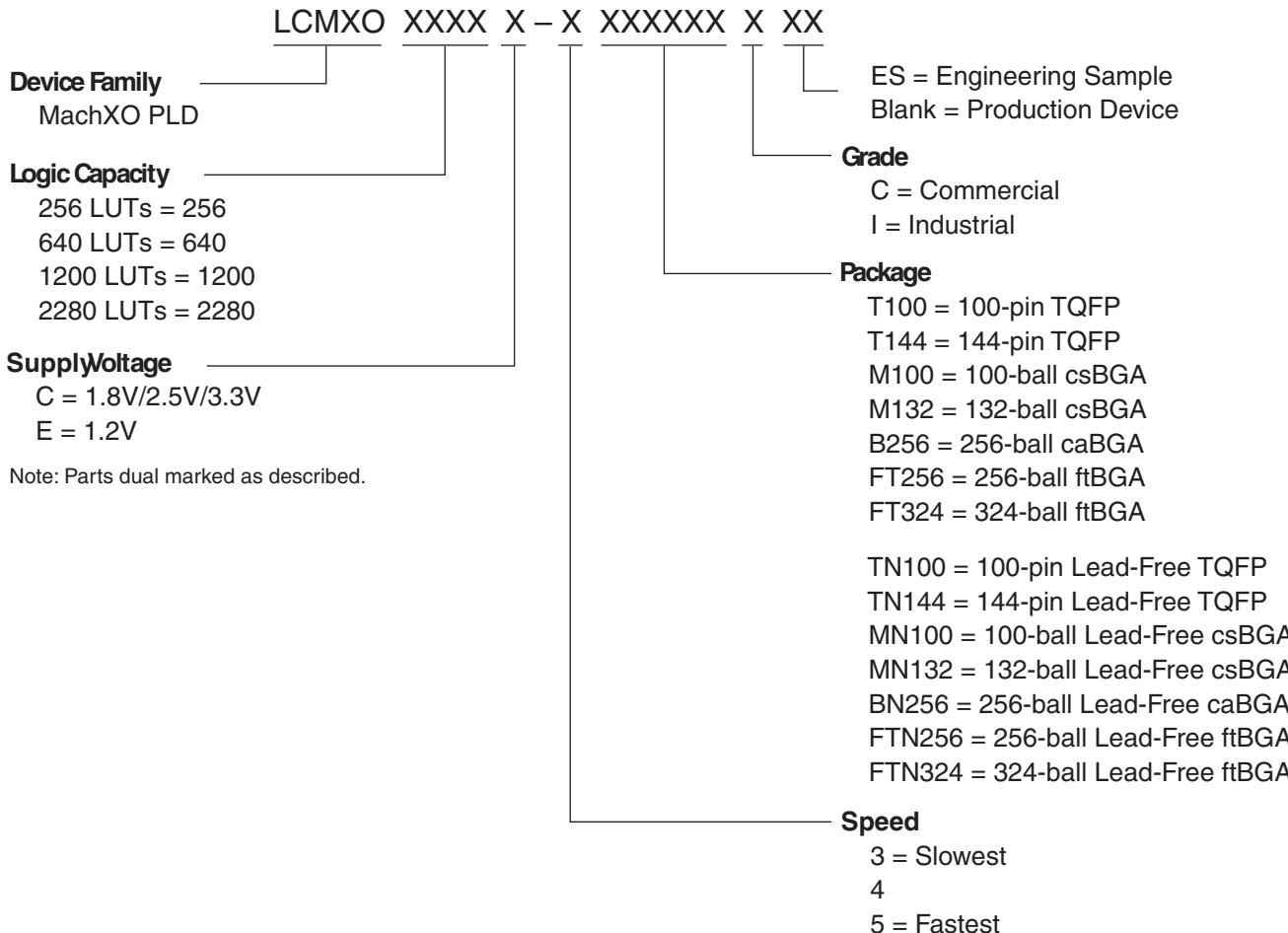
MachXO Family Data Sheet

Ordering Information

June 2013

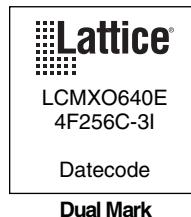
Data Sheet DS1002

Part Number Description



Ordering Information

Note: MachXO devices are dual marked except the slowest commercial speed grade device.
For example the commercial speed grade LCMXO640E-4F256C is also marked with industrial grade -3I grade.
The slowest commercial speed grade does not have industrial markings.
The markings appears as follows:



Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMxo256E-3T100I	256	1.2V	78	-3	TQFP	100	IND
LCMxo256E-4T100I	256	1.2V	78	-4	TQFP	100	IND
LCMxo256E-3M100I	256	1.2V	78	-3	csBGA	100	IND
LCMxo256E-4M100I	256	1.2V	78	-4	csBGA	100	IND

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMxo640E-3T100I	640	1.2V	74	-3	TQFP	100	IND
LCMxo640E-4T100I	640	1.2V	74	-4	TQFP	100	IND
LCMxo640E-3M100I	640	1.2V	74	-3	csBGA	100	IND
LCMxo640E-4M100I	640	1.2V	74	-4	csBGA	100	IND
LCMxo640E-3T144I	640	1.2V	113	-3	TQFP	144	IND
LCMxo640E-4T144I	640	1.2V	113	-4	TQFP	144	IND
LCMxo640E-3M132I	640	1.2V	101	-3	csBGA	132	IND
LCMxo640E-4M132I	640	1.2V	101	-4	csBGA	132	IND
LCMxo640E-3B256I	640	1.2V	159	-3	caBGA	256	IND
LCMxo640E-4B256I	640	1.2V	159	-4	caBGA	256	IND
LCMxo640E-3FT256I	640	1.2V	159	-3	ftBGA	256	IND
LCMxo640E-4FT256I	640	1.2V	159	-4	ftBGA	256	IND

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMxo1200E-3T100I	1200	1.2V	73	-3	TQFP	100	IND
LCMxo1200E-4T100I	1200	1.2V	73	-4	TQFP	100	IND
LCMxo1200E-3T144I	1200	1.2V	113	-3	TQFP	144	IND
LCMxo1200E-4T144I	1200	1.2V	113	-4	TQFP	144	IND
LCMxo1200E-3M132I	1200	1.2V	101	-3	csBGA	132	IND
LCMxo1200E-4M132I	1200	1.2V	101	-4	csBGA	132	IND
LCMxo1200E-3B256I	1200	1.2V	211	-3	caBGA	256	IND
LCMxo1200E-4B256I	1200	1.2V	211	-4	caBGA	256	IND
LCMxo1200E-3FT256I	1200	1.2V	211	-3	ftBGA	256	IND
LCMxo1200E-4FT256I	1200	1.2V	211	-4	ftBGA	256	IND

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMxo2280E-3T100I	2280	1.2V	73	-3	TQFP	100	IND
LCMxo2280E-4T100I	2280	1.2V	73	-4	TQFP	100	IND
LCMxo2280E-3T144I	2280	1.2V	113	-3	TQFP	144	IND
LCMxo2280E-4T144I	2280	1.2V	113	-4	TQFP	144	IND
LCMxo2280E-3M132I	2280	1.2V	101	-3	csBGA	132	IND
LCMxo2280E-4M132I	2280	1.2V	101	-4	csBGA	132	IND
LCMxo2280E-3B256I	2280	1.2V	211	-3	caBGA	256	IND
LCMxo2280E-4B256I	2280	1.2V	211	-4	caBGA	256	IND
LCMxo2280E-3FT256I	2280	1.2V	211	-3	ftBGA	256	IND
LCMxo2280E-4FT256I	2280	1.2V	211	-4	ftBGA	256	IND
LCMxo2280E-3FT324I	2280	1.2V	271	-3	ftBGA	324	IND
LCMxo2280E-4FT324I	2280	1.2V	271	-4	ftBGA	324	IND

Lead-Free Packaging
Industrial

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMxo256C-3TN100I	256	1.8V/2.5V/3.3V	78	-3	Lead-Free TQFP	100	IND
LCMxo256C-4TN100I	256	1.8V/2.5V/3.3V	78	-4	Lead-Free TQFP	100	IND
LCMxo256C-3MN100I	256	1.8V/2.5V/3.3V	78	-3	Lead-Free csBGA	100	IND
LCMxo256C-4MN100I	256	1.8V/2.5V/3.3V	78	-4	Lead-Free csBGA	100	IND

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMxo640C-3TN100I	640	1.8V/2.5V/3.3V	74	-3	Lead-Free TQFP	100	IND
LCMxo640C-4TN100I	640	1.8V/2.5V/3.3V	74	-4	Lead-Free TQFP	100	IND
LCMxo640C-3MN100I	640	1.8V/2.5V/3.3V	74	-3	Lead-Free csBGA	100	IND
LCMxo640C-4MN100I	640	1.8V/2.5V/3.3V	74	-4	Lead-Free csBGA	100	IND
LCMxo640C-3TN144I	640	1.8V/2.5V/3.3V	113	-3	Lead-Free TQFP	144	IND
LCMxo640C-4TN144I	640	1.8V/2.5V/3.3V	113	-4	Lead-Free TQFP	144	IND
LCMxo640C-3MN132I	640	1.8V/2.5V/3.3V	101	-3	Lead-Free csBGA	132	IND
LCMxo640C-4MN132I	640	1.8V/2.5V/3.3V	101	-4	Lead-Free csBGA	132	IND
LCMxo640C-3BN256I	640	1.8V/2.5V/3.3V	159	-3	Lead-Free caBGA	256	IND
LCMxo640C-4BN256I	640	1.8V/2.5V/3.3V	159	-4	Lead-Free caBGA	256	IND
LCMxo640C-3FTN256I	640	1.8V/2.5V/3.3V	159	-3	Lead-Free ftBGA	256	IND
LCMxo640C-4FTN256I	640	1.8V/2.5V/3.3V	159	-4	Lead-Free ftBGA	256	IND

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMxo1200C-3TN100I	1200	1.8V/2.5V/3.3V	73	-3	Lead-Free TQFP	100	IND
LCMxo1200C-4TN100I	1200	1.8V/2.5V/3.3V	73	-4	Lead-Free TQFP	100	IND
LCMxo1200C-3TN144I	1200	1.8V/2.5V/3.3V	113	-3	Lead-Free TQFP	144	IND
LCMxo1200C-4TN144I	1200	1.8V/2.5V/3.3V	113	-4	Lead-Free TQFP	144	IND
LCMxo1200C-3MN132I	1200	1.8V/2.5V/3.3V	101	-3	Lead-Free csBGA	132	IND
LCMxo1200C-4MN132I	1200	1.8V/2.5V/3.3V	101	-4	Lead-Free csBGA	132	IND
LCMxo1200C-3BN256I	1200	1.8V/2.5V/3.3V	211	-3	Lead-Free caBGA	256	IND
LCMxo1200C-4BN256I	1200	1.8V/2.5V/3.3V	211	-4	Lead-Free caBGA	256	IND
LCMxo1200C-3FTN256I	1200	1.8V/2.5V/3.3V	211	-3	Lead-Free ftBGA	256	IND
LCMxo1200C-4FTN256I	1200	1.8V/2.5V/3.3V	211	-4	Lead-Free ftBGA	256	IND

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMxo2280C-3TN100I	2280	1.8V/2.5V/3.3V	73	-3	Lead-Free TQFP	100	IND
LCMxo2280C-4TN100I	2280	1.8V/2.5V/3.3V	73	-4	Lead-Free TQFP	100	IND
LCMxo2280C-3TN144I	2280	1.8V/2.5V/3.3V	113	-3	Lead-Free TQFP	144	IND
LCMxo2280C-4TN144I	2280	1.8V/2.5V/3.3V	113	-4	Lead-Free TQFP	144	IND
LCMxo2280C-3MN132I	2280	1.8V/2.5V/3.3V	101	-3	Lead-Free csBGA	132	IND
LCMxo2280C-4MN132I	2280	1.8V/2.5V/3.3V	101	-4	Lead-Free csBGA	132	IND
LCMxo2280C-3BN256I	2280	1.8V/2.5V/3.3V	211	-3	Lead-Free caBGA	256	IND
LCMxo2280C-4BN256I	2280	1.8V/2.5V/3.3V	211	-4	Lead-Free caBGA	256	IND
LCMxo2280C-3FTN256I	2280	1.8V/2.5V/3.3V	211	-3	Lead-Free ftBGA	256	IND
LCMxo2280C-4FTN256I	2280	1.8V/2.5V/3.3V	211	-4	Lead-Free ftBGA	256	IND
LCMxo2280C-3FTN324I	2280	1.8V/2.5V/3.3V	271	-3	Lead-Free ftBGA	324	IND
LCMxo2280C-4FTN324I	2280	1.8V/2.5V/3.3V	271	-4	Lead-Free ftBGA	324	IND



MachXO Family Data Sheet

Supplemental Information

June 2013

Data Sheet DS1002

For Further Information

A variety of technical notes for the MachXO family are available on the Lattice web site.

- TN1091, [MachXO sysIO Usage Guide](#)
- TN1089, [MachXO sysCLOCK Design and Usage Guide](#)
- TN1092, [Memory Usage Guide for MachXO Devices](#)
- TN1090, [Power Estimation and Management for MachXO Devices](#)
- TN1086, [MachXO JTAG Programming and Configuration User's Guide](#)
- TN1087, [Minimizing System Interruption During Configuration Using TransFR Technology](#)
- TN1097, [MachXO Density Migration](#)
- AN8066, [Boundary Scan Testability with Lattice sysIO Capability](#)

For further information on interface standards refer to the following web sites:

- JEDEC Standards (LVTTL, LVCMOS): [www.jedec.org](#)
- PCI: [www.pcisig.com](#)



MachXO Family Data Sheet

Revision History

June 2013

Data Sheet DS1002

Revision History

Date	Version	Section	Change Summary
February 2005	01.0	—	Initial release.
October 2005	01.1	Introduction	Distributed RAM information in family table updated. Added footnote 1 - fpBGA packaging to the family selection guide.
		Architecture	sysIO Buffer section updated.
			Hot Socketing section updated.
			Sleep Mode section updated.
			SLEEP Pin Characteristics section updated.
			Oscillator section updated.
		DC and Switching Characteristics	Security section updated.
			Recommended Operating Conditions table updated.
			DC Electrical Characteristics table updated.
			Supply Current (Sleep Mode) table added with LCMXO256/640 data.
			Supply Current (Standby) table updated with LCMXO256/640 data.
			Initialization Supply Current table updated with LCMXO256/640 data.
			Programming and Erase Flash Supply Current table updated with LCMXO256/640 data.
			Register-to-Register Performance table updated (rev. A 0.16).
			External Switching Characteristics table updated (rev. A 0.16).
			Internal Timing Parameter table updated (rev. A 0.16).
			Family Timing Adders updated (rev. A 0.16).
			sysCLOCK Timingupdated (rev. A 0.16).
			MachXO "C" Sleep Mode Timing updated (A 0.16).
		Pinout Information	JTAG Port Timing Specification updated (rev. A 0.16).
			SLEEPIN description updated.
			Pin Information Summary updated.
			Power Supply and NC Connection table has been updated.
		Ordering Information	Logic Signal Connection section has been updated to include all devices/packages.
			Part Number Description section has been updated.
			Ordering Part Number section has been updated (added LCMXO256C/ LCMXO640C "4W").
		Supplemental Information	MachXO Density Migration Technical Note (TN1097) added.
November 2005	01.2	Pinout Information	Added "Power Supply and NC Connections" summary information for LCMXO1200 and LCMXO2280 in 100 TQFP package.
December 2005	01.3	DC and Switching Characteristics	Supply Current (Standby) table updated with LCMXO1200/2280 data.
		Ordering Information	Ordering Part Number section updated (added LCMXO2280C "4W").
April 2006	02.0	Introduction	Introduction paragraphs updated.
		Architecture	Architecture Overview paragraphs updated.

© 2013 Lattice Semiconductor Corp. All Lattice trademarks, registered trademarks, patents, and disclaimers are as listed at www.latticesemi.com/legal. All other brand or product names are trademarks or registered trademarks of their respective holders. The specifications and information herein are subject to change without notice.